



Ultra-Small nRF52833 Module MS88SF3 Specification



MS88SF3 is advanced, compact (18.5mm × 12.5mm × 2mm), highly flexible, ultra-low power wireless BLE 5.1 Module based on nRF52833 SoCs. Its powerful 32-bit ARM Cortex™ M4 CPU, a 512KB flash memory, a 128KB RAM and integrating a 2.4 GHz transceiver offers the perfect solution for Bluetooth connectivity.

Features

Complete RF solution with integrated antenna
BLE 5.1 data rate: 2Mbps, 1Mbps, 500kbps, 125kbps.
IEEE 802.15.4 Thread and Zigbee data rate: 250kbps
Proprietary 2.4 GHz: 2 Mbps, 1 Mbps
Integrated DC-DC converter, inductors on board.
4.9 mA peak current in TX(0 dBm)
4.6 mA peak current in RX
15 level low-comparator with wake-up from System OFF mode
Over-the-Air(OTA) firmware update
Flash/RAM: 512KB/128KB
GPIO:42
2×UART/4×SPI masters/3×SPI slaves
Operating temperature: -40°C to +105°C
SoC TX power: programmable +8dBm to -20dBm
SoC Receiver Sensitivity: -103 dBm at 125Kbps
Temperature sensor
Antenna: PCB trace
Module size: 18.5mm × 12.5mm × 2.0mm
Range:
1Mbps: up to 250 meters in open space.
125kbps: up to 300 meters in open space

Applications

Medical devices
Heart rate monitor
Blood pressure monitor
Blood glucose meter
Thermometer
Sport facilities
Weighing machine
Sports and fitness sensors
Accessories
3D glasses and gaming controller
Mobile accessories
Remote controllers / Toys
Electronic devices
Cycle computer

Certification

Full Bluetooth Declaration ID: D050415
FCC ID: 2ABU6-MS88SF3
CE ID: BLA-RF-202004-A72

Revision history

Version	Date	Notes	Contributor (s)	Person of Approve
1.0	2020.06.22	1.First edition	Eddie	Coral

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1. Product introduction

MS88SF3 series are advanced, compact (18.5mm × 12.5mm × 2.0mm), highly flexible, ultra-low power wireless BLE 5.1 Module based on nRF52833 SoCs. Its powerful 32-bit ARM Cortex™ M4 with FPU, a 512KB flash memory, a 128KB RAM and integrating a 2.4 GHz transceiver can offers the perfect solution for Bluetooth connectivity.

Fully qualified BLE stacks for nRF52833 are implemented in the S140 SoftDevices which can be freely downloaded. In the meantime, ANT, ZIGBEE and THREAD applications can be supported by nRF52833 with extensive software.

MS88SF3 can meet the most demanding applications, it allow faster time to market with high performance, low power management and reduced development cost. Also, its range is estimated up to 250 meters in open space for 1Mbps data rate; up to 120 meters in open space for 2 Mbps data rate.

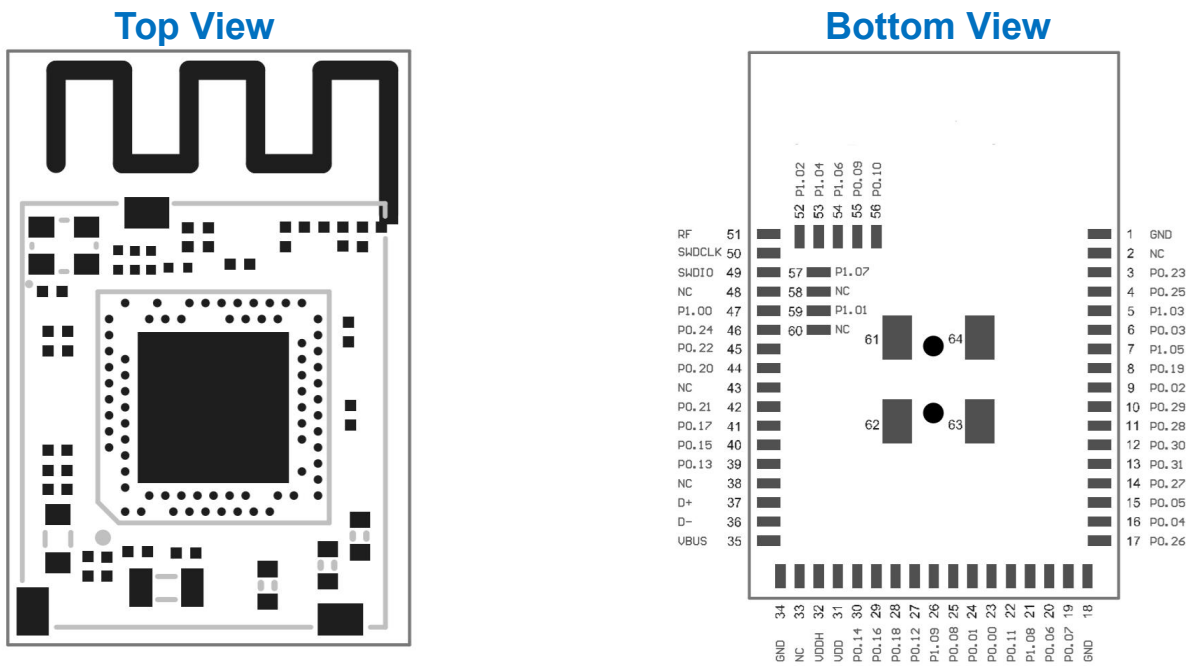
1.1 Ordering information

Ordering number	Description
MS88SF3	nRF52833-QIAA BT 5.1 Module, PCB Antenna, Reel pack

2. Pin description

2.1 Pin assignment

2.1.1 MS88SF3



2.2 Pin definition

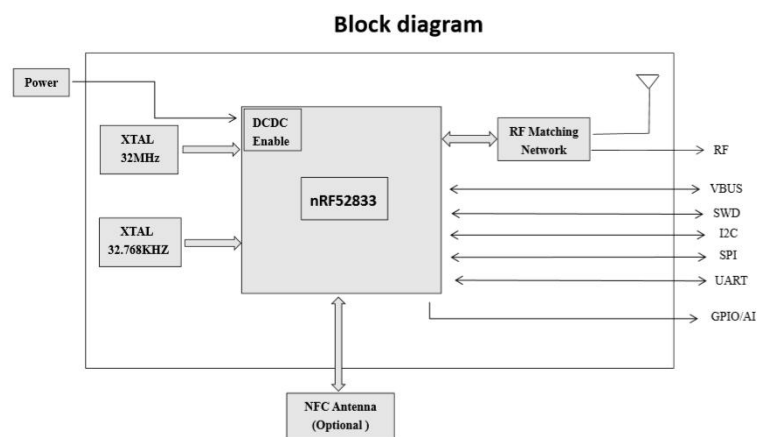
Symbol	Type	Description
VDD	Power	Power supply, 1.7V-3.6V
VDDH	Power	Power supply, 2.5V-5.5V
VBUS	Power	USB Power Supply, 4.35V-5.5V
D+	Digital I/O	USB D+
D-	Digital I/O	USB D-
GND	Power	Ground
SWDIO	Digital I/O	Hardware debug and flash/programming I/O
SWCLK	Digital input (debug)	Hardware debug and flash programming I/O
P 0.31	Digital I/O	General purpose I/O
AIN7	Analog input	Analog input
P 0.29	Digital I/O	General purpose I/O

AIN5	Analog input	Analog input
P 0.02	Digital I/O	General purpose I/O
AIN0	Analog input	Analog input
P0.19	Digital I/O	General purpose I/O
P1.05	Digital I/O	General purpose I/O
P0.25	Digital I/O	General purpose I/O
P0.30	Digital I/O	General purpose I/O
AIN6	Analog input	Analog input
P0.28	Digital I/O	General purpose I/O
AIN4	Analog input	Analog input
P0.03	Digital I/O	General purpose I/O
AIN1	Analog input	Analog input
P1.03	Digital I/O	General purpose I/O
P0.23	Digital I/O	General purpose I/O
P0.00	Digital I/O	General purpose I/O
XL1	Analog input	Connection for 32.768 kHz crystal
P0.01	Digital I/O	General purpose I/O
XL2	Analog input	Connection for 32.768 kHz crystal
P0.26	Digital I/O	General purpose I/O
P0.27	Digital I/O	General purpose I/O
P0.04	Digital I/O	General purpose I/O
AIN2	Analog input	Analog input
P0.10	Digital I/O	General purpose I/O
NFC2	NFC input	NFC antenna connection
P0.05	Digital I/O	General purpose I/O
AIN3	Analog input	Analog input
P0.06	Digital I/O	General purpose I/O
P0.09	Digital I/O	General purpose I/O
NFC1	NFC input	NFC antenna connection
P0.07	Digital I/O	General purpose I/O
TRACECLK	Trace clock	Trace buffer clock
P0.08	Digital I/O	General purpose I/O
P1.08	Digital I/O	General purpose I/O
P1.07	Digital I/O	General purpose I/O
P1.09	Digital I/O	General purpose I/O
TRACEDATA3	Trace data	Trace buffer TRACEDATA[3]
P1.06	Digital I/O	General purpose I/O
P0.11	Digital I/O	General purpose I/O
TRACEDATA2	Trace data	Trace buffer TRACEDATA[2]
P0.12	Digital I/O	General purpose I/O
TRACEDATA1	Trace data	Trace buffer TRACEDATA[1]
P1.04	Digital I/O	General purpose I/O
P1.02	Digital I/O	General purpose I/O

P1.01	Digital I/O	General purpose I/O
P0.14	Digital I/O	General purpose I/O
P0.16	Digital I/O	General purpose I/O
P0.18	Digital I/O	General purpose I/O
nRESET		Configurable as pin RESET
P0.21	Digital I/O	General purpose I/O
P0.13	Digital I/O	General purpose I/O
P0.15	Digital I/O	General purpose I/O
P0.17	Digital I/O	General purpose I/O
P0.20	Digital I/O	General purpose I/O
P0.22	Digital I/O	General purpose I/O
P0.24	Digital I/O	General purpose I/O
P1.00 TRACEDATA0	Digital I/O	General purpose I/O
	Trace data	Trace buffer TRACEDATA[0]
		Serial wire output (SWO)

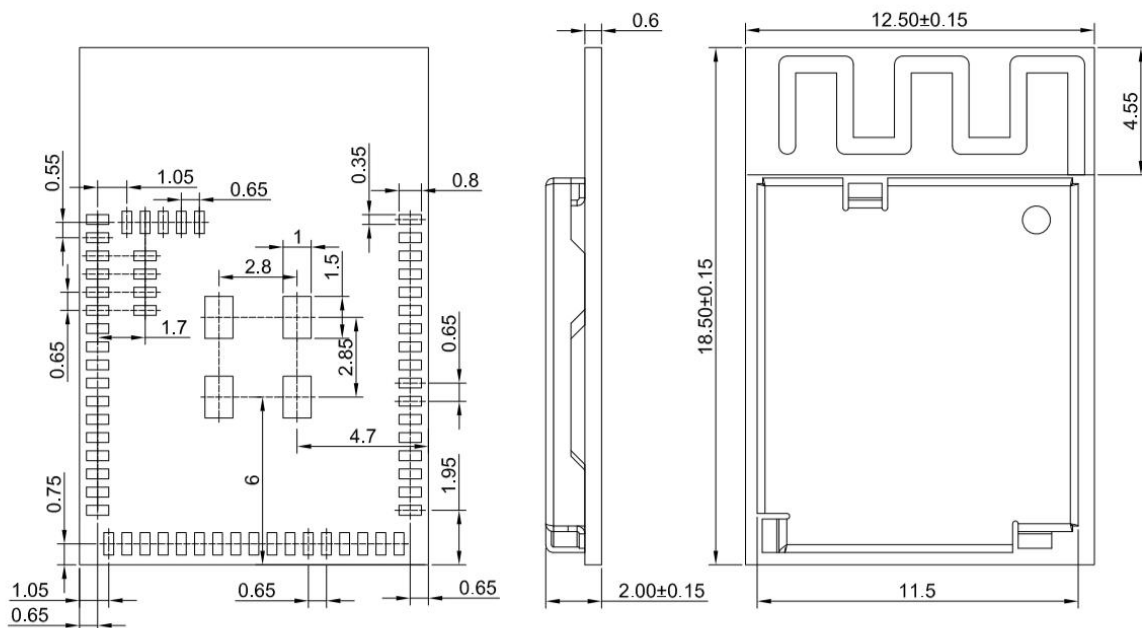
2.3 Block diagram

2.3.1 MS88SF3



2.4 Mechanical drawing

2.4.1 MS88SF3/PCB Antenna



Unit: mm

Tolerance: +/- 0.1, default

3. Electrical specification

The electrical specifications of the module are directly related to the Nordic semiconductor Specifications for the nRF52833 chipset. The below information is only the extract from nRF52833 specification. For more detailed information, please refer to the up-to-date specification of the chipset available on the Nordic semiconductor website.

3.1 Absolute maximum ratings

	Note	Min.	Max	Unit
Supply voltages				
VDD		-0.3	+3.9	V
VDDH		-0.3	+5.8	V

VBUS		-0.3	+5.8	V
VSS			0	V
I/O Pin voltage				
$V_{I/O}, VDD \leq 3.6V$		-0.3	$VDD + 0.3V$	V
$V_{I/O}, VDD > 3.6V$		-0.3	3.9V	V
NFC antenna pin current				
$I_{NFC1/2}$			80	mA
Environmental (AQFN package)				
Storage temperature		-40	+125	°C
MSL	Moisture Sensitivity Level		2	
ESD HBM	Human Body Model		4	KV
ESD HBM Class	Human Body Model Class		3A	
ESD CDM	Charged Device Model		750	V
Flash memory				
Endurance		10 000		write/erase cycles
Retention at 85 °C		10		years
Retention at 105 °C	Limited to 1000 write/erase cycles	3		years
Retention at 105 °C -85 °C, execution split	Limited to 1000 write/erase cycles	6.7		years

Notes: Maximum ratings are the extreme limits to which the chip can be exposed for a limited amount of time without permanently damaging it. Exposure to absolute maximum ratings for prolonged periods of time may affect the reliability of the device.⁴²

3.2 Recommended operating conditions

Symbol	Parameter	Min.	Nom.	Max.	Units
VDD	VDD supply voltage, independent of DCDC enable	1.7	3.0	3.6	V
VDD _{POR}	VDD supply voltage needed during power-on reset	1.75			V
VDDH	VDDH supply voltage, independent of DCDC enable	2.5	3.7	5.5	V
VBUS	VBUS USB supply voltage	4.35	5.0	5.5	V
t_{R_VDD}	Supply rise time (0 V to 1.7 V)			60	ms
t_{R_VDDH}	Supply rise time (0 V to 3.7 V)			100	ms
TA	Operating temperature	-40	25	85	°C
TA _{EXT}	Extended operating temperature	85		105	°C

T_J	Junction temperature			110	°C
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Important : The On-chip power-on reset circuitry may not function properly for rise times longer than the specified maximum.

3.3 Electronic characteristic

3.3.1 General radio characteristics

Symbol	Description	Min.	Nom.	Max.	Units
f_{OP}	Operating frequencies	2360		2500	MHz
$f_{PLL,CH,SP}$	PLL channel spacing		1		MHz
$f_{DELTA,1M}$	Frequency deviation@1 Mbps		±170		kHz
$f_{DELTA,BLE,1M}$	Frequency deviation @ BLE 1Mbps		±250		kHz
$f_{DELTA,2M}$	Frequency deviation @ 2Mbps		±320		kHz
$f_{DELTA,BLE,2M}$	Frequency deviation@ BLE 2Mbps		±500		kHz
f_{skBPS}	On-the-air data rate	125		2000	kbps
$f_{chip,IEEE 802.15.4}$	Chip rate in IEEE 802.15.4 mode		2000		kchipAs

3.3.2 Radio current consumption (Transmitter)

Symbol	Description	Min.	Typ.	Max.	Units
$I_{TX,PLUS8dBm,DCDC}$	TX only run current(DCDC,3V) $P_{RF}=+ 8$ dBm		14.2		mA
$I_{TX,PLUS8dBm}$	TX only run current $P_{RF} =+ 8$ dBm		30.4		mA
$I_{TX,PLUS4dBm,DCDC}$	TX only run current(DCDC,3V) $P_{RF} =+ 4$ dBm		9.6		mA
$I_{TX,PLUS4dBm}$	TX only run current $P_{RF} =+ 4$ dBm		20.7		mA
$I_{TX,0dBm,DCDC}$	TX only run current (DC/DC, 3 V) $P_{RF} =0$ dBm		4.9		mA
$I_{TX,0dBm}$	TX only run current $P_{RF} = 0$ dBm		10.3		mA
$I_{TX,MINUS4dBm,DCDC}$	TX only run current DCDC,3V $P_{RF} =-4$ dBm		3.8		mA
$I_{TX,MINUS4dBm}$	TX only run current $P_{RF} =-4$ dBm		8.0		mA
$I_{TX,MINUS8dBm,DCDC}$	TX only run current DCDC,3V $P_{RF} =-8$ dBm		3.4		mA
$I_{TX,MINUS8dBm}$	TX only run current $P_{RF} =-8$ dBm		7.1		mA

$I_{TX,MINUS12dBm,DCDC}$	TX only run current DCDC,3V $P_{RF} = -12$ dBm		3.1		mA
$I_{TX,MINUS12dBm}$	TX only run current $P_{RF} = -12$ dBm		6.4		mA
$I_{TX,MINUS16dBm,DCDC}$	TX only run current DCDC,3V $P_{RF} = -16$ dBm		2.9		mA
$I_{TX,MINUS16dBm}$	TX only run current $P_{RF} = -16$ dBm		5.9		mA
$I_{TX,MINUS20dBm,DCDC}$	TX only run current DCDC,3V $P_{RF} = -20$ dBm		2.7		mA
$I_{TX,MINUS20dBm}$	TX only run current $P_{RF} = -20$ dBm		5.5		mA
$I_{TX,MINUS40dBm,DCDC}$	TX only run current DCDC,3V $P_{RF} = -40$ dBm		2.3		mA
$I_{TX,MINUS40dBm,}$	TX only run current $P_{RF} = -40$ dBm		4.5		mA
$I_{START,TX,DCDC}$	TX start-up current DCDC,3V $P_{RF} = 4$ dBm		4.3		mA
$I_{START,TX}$	TX start-up current $P_{RF} = 4$ dBm		8.9		mA

3.3.3 Radio current consumption (Receiver)

Symbol	Description	Min	Typ.	Max.	Units
$I_{RX,1M,DCDC}$	RX only run current(DCDC,3V)1Mbps/1Mbps BLE		4.6		mA
$I_{RX,1M}$	RX only run current(LDO,3V)1Mbps/1Mbps BLE		9.6		mA
$I_{RX,2M,DCDC}$	RX only run current(DCDC,3V)2Mbps/2Mbps BLE		5.2		mA
$I_{RX,2M,}$	RX only run current(LDO,3V)2Mbps/2Mbps BLE		10.7		mA
$I_{START,RX,1M,DCDC}$	RX start-up current(DCDC,3V)1Mbps/1Mbps BLE		3.4		mA
$I_{START,RX,1M}$	RX start-up current 1Mbps/1Mbps BLE		6.8		mA

3.3.4 Transmitter specification

Symbol	Description	Min	Typ.	Max.	Units
P_{RF}	Maximum output power		8		dBm
P_{RFC}	RF power control range		28		dB
P_{RFCR}	RF power accuracy			± 4	dB
$P_{RF1,1}$	1st adjacent channel transmit power 1 MHz(1 Mbps)		-25		dBc
$P_{RF2,1}$	2nd adjacent channel transmit power 2 MHz(1 Mbps)		-54		dBc
$P_{RF1,2}$	1st adjacent channel transmit power 2 MHz(2 Mbps)		-26		dBc
$P_{RF2,2}$	2nd adjacent channel transmit power 4 MHz(2 Mbps)		-54		dBc
E_{vm}	Error Vector Magnitude IEEE 802.15.4		9		%rms
$P_{harm2nd,IEEE}$ 802.15.4	2 nd Harmonics in IEEE 802.15.4 mode		-51		dBm

$P_{\text{harm3rd,IEEE 802.15.4}}$	3 rd Harmonics in IEEE 802.15.4		-51		dBm
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3.3.5 Receiver operation

Symbol	Description	Min	Typ.	Max.	Units
$P_{\text{RX,MAX}}$	Maximum received signal strength at <0.1% PER		0		dBm
$P_{\text{SENS,IT,1M}}$	Sensitivity, 1 Mbps nRF mode ¹⁶		-93		dBm
$P_{\text{SENS,IT,2M}}$	Sensitivity, 2Mbps nRF mode ¹⁷		-89		dBm
$P_{\text{SENS,IT,SP,1M,BLE}}$	Sensitivity, 1 Mbps BLE ideal transmitter, ≤ 37 bytes BER=1E-3 ²⁰		-96		dBm
$P_{\text{SENS,IT,LP,1M,BLE}}$	Sensitivity, 1 Mbps BLE ideal transmitter, ≥ 128 bytes BER=1E-4 ²¹		-94		dBm
$P_{\text{SENS,IT,SP,2M,BLE}}$	Sensitivity, 2 Mbps BLE ideal transmitter, Packet length ≤ 37 bytes		-92		dBm
$P_{\text{SENS,IT,BLE}}$ LE125K	Sensitivity, 125kbps BLE mode		-103		dBm
$P_{\text{SENS,IT,BLE}}$ LE500K	Sensitivity, 500kbps BLE mode		-98		dBm
$P_{\text{SENSE,IEEE}}$ 802.15.4	Sensitivity in IEEE 802.15.4 mode		-100		dBm

3.3.6 RX selectivity

Symbol	Description	Min	Typ.	Max.	Units
$C/I_{1\text{M,co-channel}}$	1Mbps mode, Co-Channel interference		10		dB
$C/I_{1\text{M,-1MHz}}$	1 Mbps mode, Adjacent (-1 MHz) interference		-5		dB
$C/I_{1\text{M,+1MHz}}$	1 Mbps mode, Adjacent (+1 MHz) interference		-14		dB
$C/I_{1\text{M,-2MHz}}$	1 Mbps mode, Adjacent (-2 MHz) interference		-19		dB
$C/I_{1\text{M,+2MHz}}$	1 Mbps mode, Adjacent (+2 MHz) interference		-42		dB
$C/I_{1\text{M,-3MHz}}$	1 Mbps mode, Adjacent (-3 MHz) interference		-37		dB
$C/I_{1\text{M,+3MHz}}$	1 Mbps mode, Adjacent (+3 MHz) interference		-47		dB
$C/I_{1\text{M,}\pm 6\text{MHz}}$	1 Mbps mode, Adjacent (≥ 6 MHz) interference		-52		dB
$C/I_{1\text{MBLE,co-channel}}$	1 Mbps BLE mode, Co-Channel interference		6		dB
$C/I_{1\text{MBLE,-1MHz}}$	1 Mbps BLE mode, Adjacent (-1 MHz) interference		-2		dB
$C/I_{1\text{MBLE,+1MHz}}$	1 Mbps BLE mode, Adjacent (+1 MHz) interference		-10		dB
$C/I_{1\text{MBLE,-2MHz}}$	1 Mbps BLE mode, Adjacent (-2 MHz) interference		-23		dB

C/I _{1MBLE,+2MHz}	1 Mbps BLE mode, Adjacent (+2 MHz) interference		-45		dB
C/I _{1MBLE,>3MHz}	1 Mbps BLE mode, Adjacent (≥ 3 MHz) interference		-54		dB
C/I _{1MBLE,image}	Image frequency Interference		-24		dB
C/I _{1MBLE,image,1MHz}	Adjacent (1 MHz) interference to in-band image frequency		-37		dB
C/I _{2M,co-channel}	2Mbps mode, Co-Channel interference		10		dB
C/I _{2M,-2MHz}	2 Mbps mode, Adjacent (-2 MHz) interference		-4		dB
C/I _{2M,+2MHz}	2 Mbps mode, Adjacent (+2 MHz) interference		-16		dB
C/I _{2M,-4MHz}	2 Mbps mode, Adjacent (-4 MHz) interference		-19		dB
C/I _{2M,+4MHz}	2 Mbps mode, Adjacent (+4 MHz) interference		-46		dB
C/I _{2M,-6MHz}	2 Mbps mode, Adjacent (-6 MHz) interference		-41		dB
C/I _{2M,+6MHz}	2 Mbps mode, Adjacent (+6 MHz) interference		-48		dB
C/I _{2M,≥ 12MHz}	2 Mbps mode, Adjacent (≥ 12 MHz) interference		-52		dB
C/I _{2MBLE,co-channel}	2 Mbps BLE mode, Co-Channel interference		7		dB
C/I _{2MBLE,-2MHz}	2 Mbps BLE mode, Adjacent (-2 MHz) interference		-2		dB
C/I _{2MBLE,+2MHz}	2 Mbps BLE mode, Adjacent (+2 MHz) interference		-12		dB
C/I _{2MBLE,-4MHz}	2 Mbps BLE mode, Adjacent (-4 MHz) interference		-22		dB
C/I _{2MBLE,+4MHz}	2 Mbps BLE mode, Adjacent (+4 MHz) interference		-46		dB
C/I _{2MBLE,≥ 6MHz}	2 Mbps BLE mode, Adjacent (≥ 6 MHz) interference		-52		dB
C/I _{2MBLE,image}	Image frequency interference		-22		dB
C/I _{2MBLE,image,2MHz}	Adjacent (2 MHz) interference to in-band image frequency		-37		dB
C/I _{125k BLE LR, co-channel}	125 kbps BLE LR mode, Co-Channel interference		3		dB
C/I _{125k BLE LR,-1MHz}	125 kbps BLE LR mode, Adjacent (-1 MHz) interference		-9		dB
C/I _{125k BLE LR,+1MHz}	125 kbps BLE LR mode, Adjacent (+1 MHz) interference		-16		dB
C/I _{125k BLE LR,-2MHz}	125 kbps BLE LR mode, Adjacent (-2 MHz) interference		-27		dB
C/I _{125k BLE LR,+2MHz}	125 kbps BLE LR mode, Adjacent (+2 MHz) interference		-54		dB
C/I _{125k BLE LR,>3MHz}	125 kbps BLE LR mode, Adjacent (≥ 3 MHz) interference		-60		dB
C/I _{125k BLE LR,image}	Image frequency Interference		-27		dB
C/I _{IEEE 802.15.4,-5MHz}	IEEE 802.15.4 mode, Adjacent (-5 MHz) rejection		-33		dB
C/I _{IEEE 802.15.4,+5MHz}	IEEE 802.15.4 mode, Adjacent (+5 MHz) rejection		-38		dB

+5MHz					
C/I _{IEEE} 802.15.4,±10MHz	IEEE 802.15.4 mode, Alternate (±10 MHz) rejection		-49		dB

3.3.7 RX intermodulation

Symbol	Description	Min	Typ.	Max.	Units
P _{IMD,5TH,1M}	IMD performance, 1 Mbps, 5th offset channel, packet length ≤ 37 bytes		-34		dBm
P _{IMD,5TH,1M, BLE}	IMD performance, BLE 1 Mbps, 5th offset channel, packet length ≤ 37 bytes		-32		dBm
P _{IMD,5TH,2M}	IMD performance, 2 Mbps, 5th offset channel, packet length ≤ 37 bytes		-33		dBm
P _{IMD,5TH,2M, BLE}	IMD performance, BLE 2 Mbps, 5th offset channel, packet length ≤ 37 bytes		-32		dBm

3.3.8 Radio timing

Symbol	Description	Min	Typ.	Max.	Units
t _{TXEN,BLE,1M}	Time between TXEN task and READY event after channel FREQUENCY configured	140		140	us
t _{TXEN,FAST,BLE,1M}	Time between TXEN task and READY event after channel FREQUENCY configured (Fast Mode)	40		40	us
t _{TXDIS,BLE,1M}	When in TX, delay between DISABLE task and DISABLED event for MODE = Nrf_1Mbit and MODE = Ble_1Mbit	6		6	us
t _{TXDIS,BLE,1M}	Time between the RXEN task and READY event after channel FREQUENCY configured (1 Mbps BLE)	140		140	us
T _{rxen,FAST,BLE,1M}	Time between the RXEN task and READY event after channel FREQUENCY configured (1 Mbps BLE with fast ramp-up)	40		40	us
t _{RXDIS,BLE,1M}	When in RX, delay between DISABLE task and DISABLED event for MODE = Nrf_1Mbit and MODE = Ble_1Mbit	0		0	us
t _{TXDIS,BLE,2M}	When in TX, delay between DISABLE task and DISABLED event for MODE = Nrf_2Mbit and MODE = Ble_2Mbit	4		4	us
t _{RXDIS,BLE,2M}	When in RX, delay between DISABLE task and DISABLED event for MODE = Nrf_2Mbit and MODE = Ble_2Mbit	0		0	us
t _{TXEN,IEEE 802.15.4}	Time between TXEN task and READY event after	130		130	us

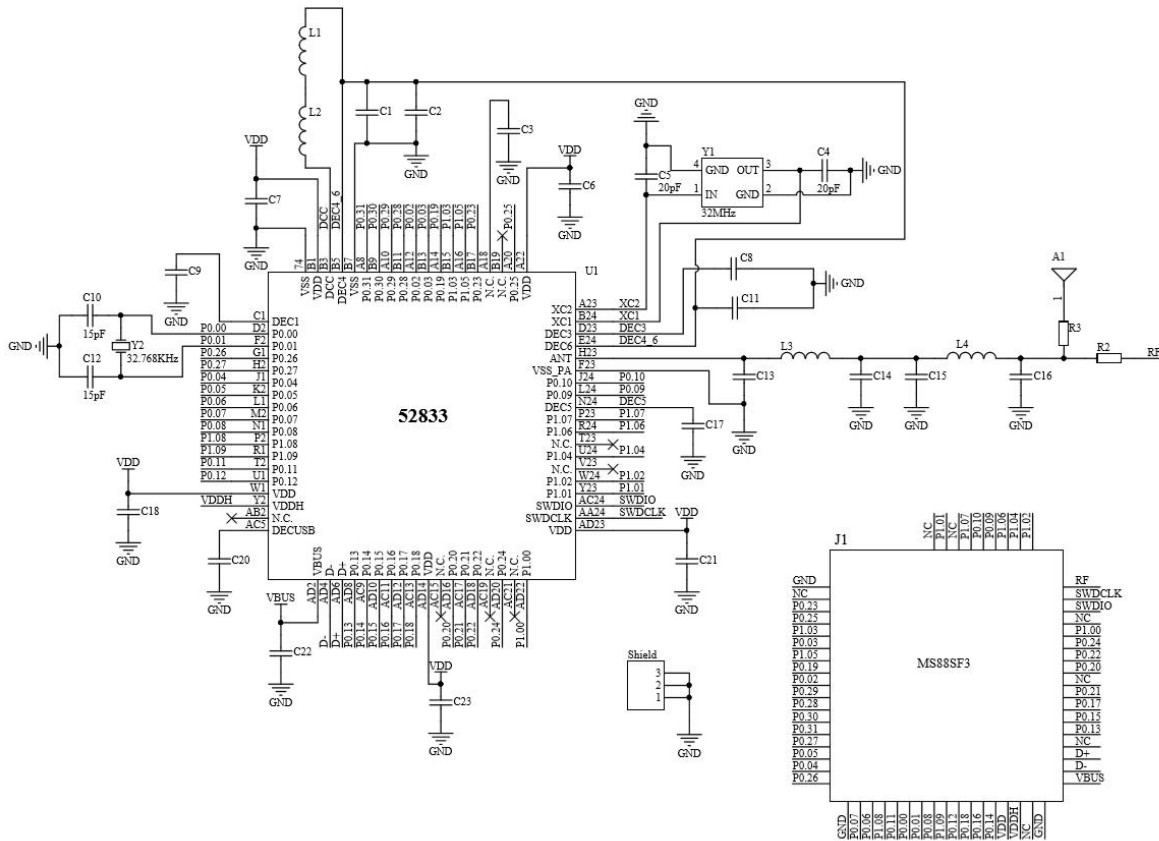
	channel FREQUENCY configured (IEEE 802.15.4)				
$t_{TXEN,FAST,IEEE\ 802.15.4}$	Time between TXEN task and READY event after channel FREQUENCY configured (IEEE 802.15.4 with fast ramp-up)	40		40	us
$t_{TXDIS,IEEE\ 802.15.4}$	When in TX, delay between DISABLE task and DISABLED event (IEEE 802.15.4)	21		21	us
$t_{RXEN,IEEE\ 802.15.4}$	Time between the RXEN task and READY event after channel FREQUENCY configured (IEEE 802.15.4)	130		130	us
$t_{RXEN,FAST,IEEE\ 802.15.4}$	Time between the RXEN task and READY event after channel FREQUENCY configured (IEEE 802.15.4 with fast ramp-up)	40		40	us
$t_{RXDIS,IEEE\ 802.15.4}$	When in RX, delay between DISABLE task and DISABLED event (IEEE 802.15.4)	0.5		0.5	us
$t_{RX-to-TX\ turnaround}$	Maximum TX-to-RX or RX-to-TX turnaround time in IEEE 802.15.4 mode		40		us

3.3.9 Received signal strength indicator (RSSI) specifications

Symbol	Description	Min	Typ.	Max.	Units
$RSSI_{ACC}$	RSSI accuracy ²²		± 2		dB
$RSSI_{RESOLUTION}$	RSSI resolution		1		dB
$RSSI_{PERIOD}$	RSSI sampling time from RSSI_START task		0.25		us
$RSSI_{SETTLE}$	RSSI settling time after signal level change		15		us

4. Electrical schematic

Default is using “DC-DC mode”(DCDCEN enabled).

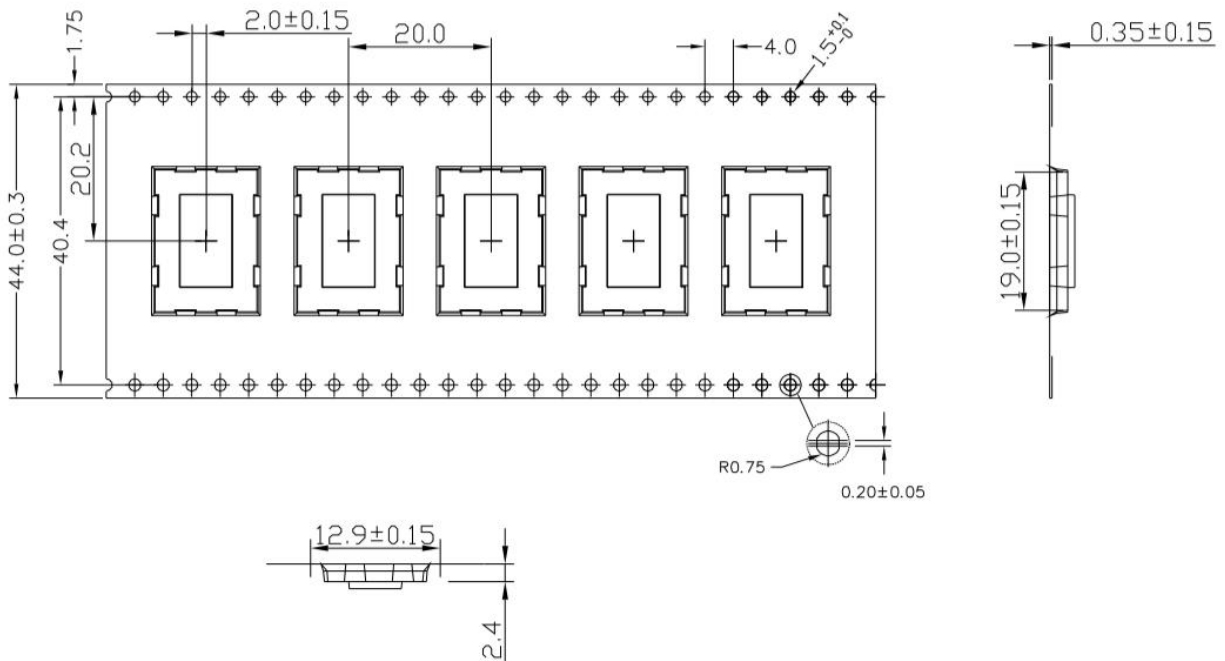
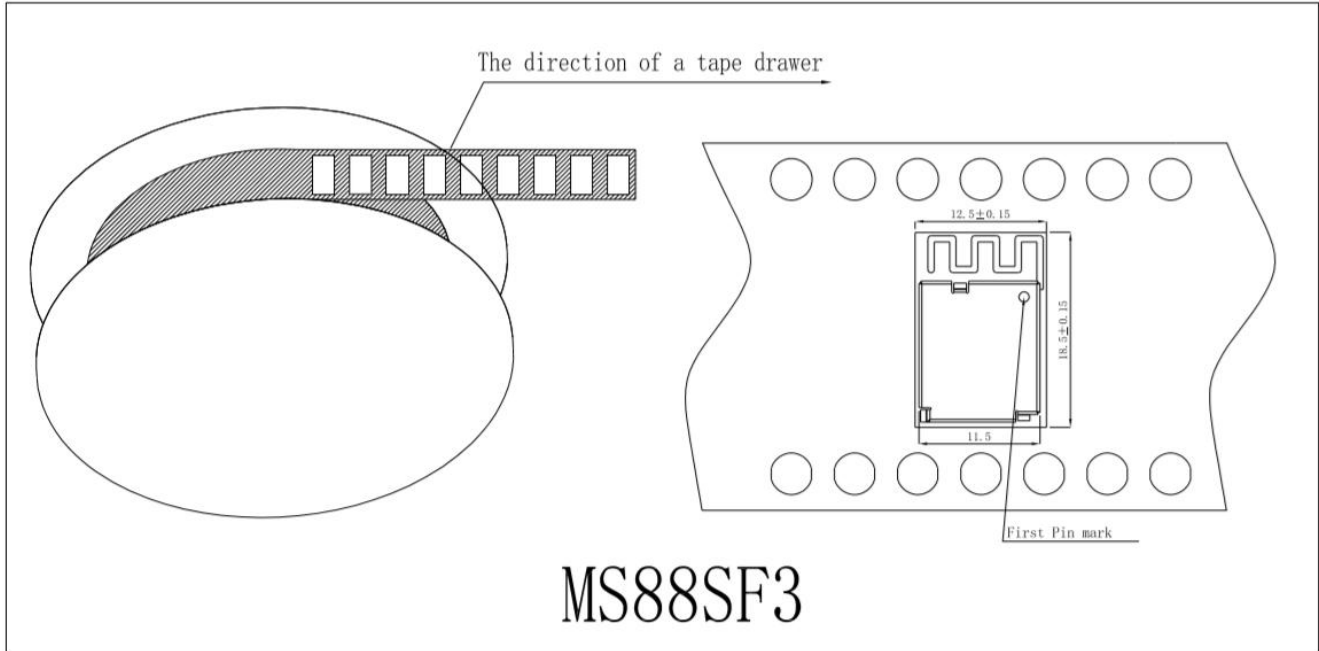


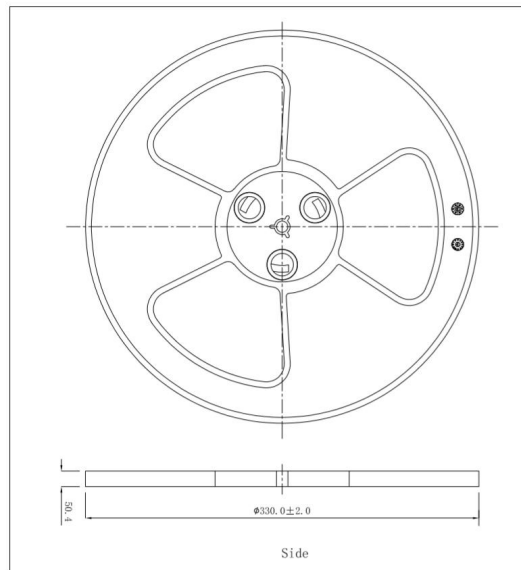
Note: The main supply voltage is connected to the VDD/VDDH pins. The module system will enter one of two supply voltage modes, normal or high voltage mode, depending on how the supply voltage is connected to these pins

- 1.Normal voltage mode is entered when the supply voltage is connected to both the VDD and VDDH pins (pin VDD shorted to pin VDDH).
- 2.High voltage mode is entered when the supply voltage is only connected to the VDDH pin and the VDD pin is not connected to any voltage supply.

5. Package information

5.1 Package dimension



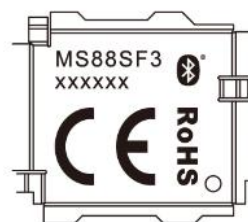


Unit: mm

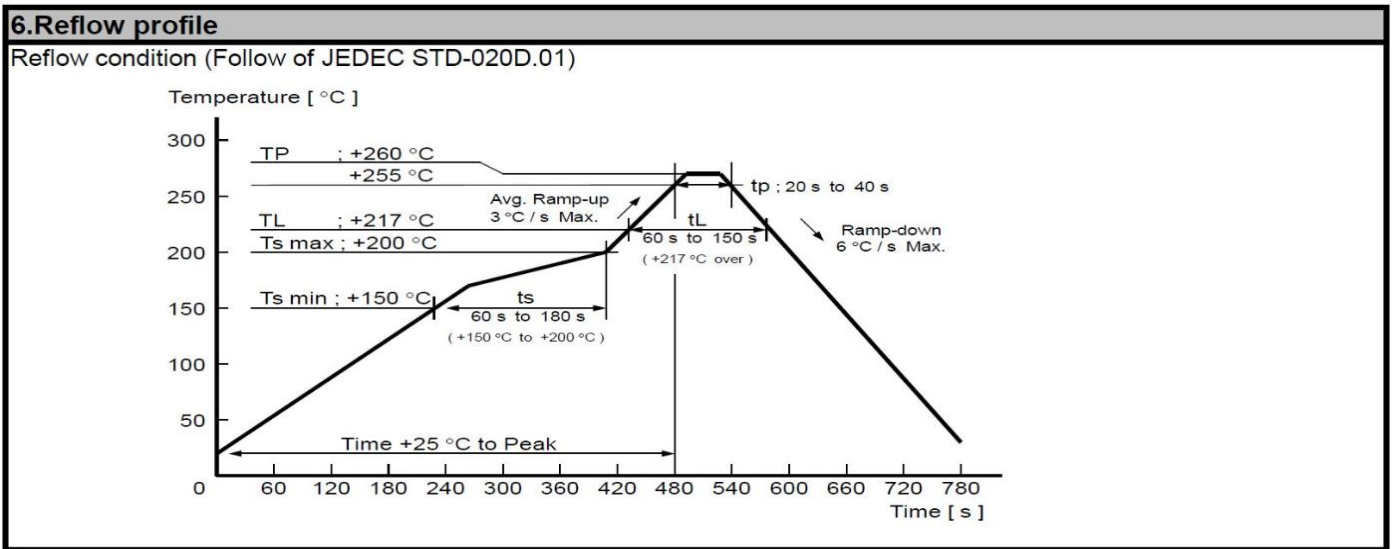
Tolerance: +/- 0.1, default

Details	Reel
Quantity(module)	650PCS
Tape Weight	460g
Single module Weight	1.1g
Gross Weight	1200g
Dimension	W: 44mm T: 0.35mm

5.2 Marking on metal shield



6. Reflow and soldering



Profile Feature	Sn-Pb Assembly	Pb-Free Assembly
Solder Paste	Sn63/Pb37	Sn96.5/Ag3/Cu0.5
Preheat Temperature min (T _{smin})	100°C	150°C
Preheat Temperature max (T _{smax})	150°C	200°C
Preheat Time (T _{smin} to T _{smax})(t _s)	60-120 sec	60-120 sec
Average ramp-up rate (T _{smax} to T _p)	3°C/second max	3°C/second max
Liquidous Temperature (T _L)	183°C	217°C
Time (t _L)Maintained Above (T _L)	60-90 sec	30-90 sec
Peak Temperature (T _p)	220-235°C	230-250°C
Average ramp-down rate (T _p to T _{smax})	6°C/second max	6°C/second max
Time 25°C to peak temperature	6 minutes max	8 minutes max

7. Certification

7.1 Full Bluetooth Declaration ID

Please kindly check the DID number for MS88SF3: D050415.

Minew technologies meet the bluetooth specification maintained by Bluetooth SIG, and all the product produced by Minew is properly tested and comply with the Bluetooth license agreements.

Minew is one of the associate member of Bluetooth SIG. The requirement of listing products by companies is

become the members of the SIG and also pay the listed fees for each product required.

Please Kindly check the below Link to know more info:

<https://www.bluetooth.com/develop-with-bluetooth/qualification-listing>.

The Minew Bluetooth Low Energy modules based on Nordic Semiconductor SoCs are listed as a “End product”.

7.2 Europe (CE)

MS88SF3 module is being tested and is expected to be compliant against the EU-Radio Equipment standards. OEM integrator should consult with qualified test house to verify all regulatory requirements have been met for their complete device.

7.3 United States (FCC)

MS88SF3 module is being tested and is expected to be compliant against the Federal Communications Commission standards.

As for the OEM integration:

Only OEM integrator have right to intend this device under the following conditions:

Any other transmitter or antenna must not be co-located with the antenna and transmitter. The module shall be only used with the integral antenna(s) that has been originally tested and certified with this module.

As long as the two conditions below are met, further transmitter testing will not be required.

(1) This device may not cause harmful interference, and

(2) this device must accept any interference received, including interference that may cause undesired operation.

However, the OEM integrator shall test their end-product for any additional compliance requirements with this module installed (for example, digital device emission, PC peripheral requirements, etc.).

If these conditions cannot be met (for example certain laptop configuration or co-location with another transmitter), then the FCC authorization for this module in combination with the host equipment is no longer considered valid and the final product shall not use the FCC ID of the module. In these circumstances, the OEM integrator shall be re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

The OEM shall be verifying end product compliance with FCC Part 15, sub-part B limits for unintentional radiators through an accredited test facility.

7.4 Environmental

7.4.1 RoHS

MS88SF3 modules are in compliance with Directive 2011/65/EU, 2015/863/EU of the European Parliament and the Council on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

8. Hardware

8.1 USB interface

Modules based on nRF52810, nRF52822 and nRF52832 with no USB interface whereas modules based on nRF52840 and nRF52833 with USB interface.

8.1.1 USB operating conditions

Symbol	Description	Min	Typ.	Max.	Units
V _{BUS}	Supply voltage on VBUS pin.	4.35	5	5.5	V
V _{DPDM}	Voltage on D+ and D- lines	VSS-0.3V		VUSB33 +0.3	V

8.1.2 USB regulation specifications

Symbol	Description	Min	Typ.	Max.	Units
I _{USB,QUIES}	USB regulator quiescence current drawn from Vbus (USB D enabled)		170		μA
t _{USBPWRRDY}	Time from USB enabled to USBPWRRDY event triggered, V _{BUS} supply provided		1		ms
V _{USB33}	On voltage at the USB regulator put(DECUSB pin)	3.0	3.3	3.6	V
R _{SOURCE,VBUS}	Maximum source resistance on Vbus,incl.cable			2	Ω
C _{DECUSB}	Decoupling capacitor on the DECUSB pin	2.35	4.7	5.5	μF

9. Notes & cautions

We cannot assure that the specification has no errors and omission even though this specification is under collate and check strictly.

This specification is under the protection of laws and regulations of copyright, please do not copy and duplicate at any form, or do not transmit part or full of this specification in any wire and wireless network in any form, or do not edit or translate to any other format, word, code, etc.

9.1 Design notes

(1) It is critical to following the recommendations of this document to ensure the module meets the specifications.

(2) The module should be placed at the edge of the circuit board as far as possible to keep away from other circuits.

(3) Antenna should be kept away from other circuits. It can prevent low radiation efficiency and the normal use of other circuits from being affected.

(4) The landing of components should be appropriate and that is better for reducing the parasitic inductance.

(5) Please refuse to supply voltage that is not within the range of specification.

(6) Please make sure the module or its surface may not suffer from the physical shock or extreme stress.

9.2 Layout notes

To make sure wireless performance is at its best condition, please layout the module on the carrier board as below instructions and picture.

(1) Placement of the antenna

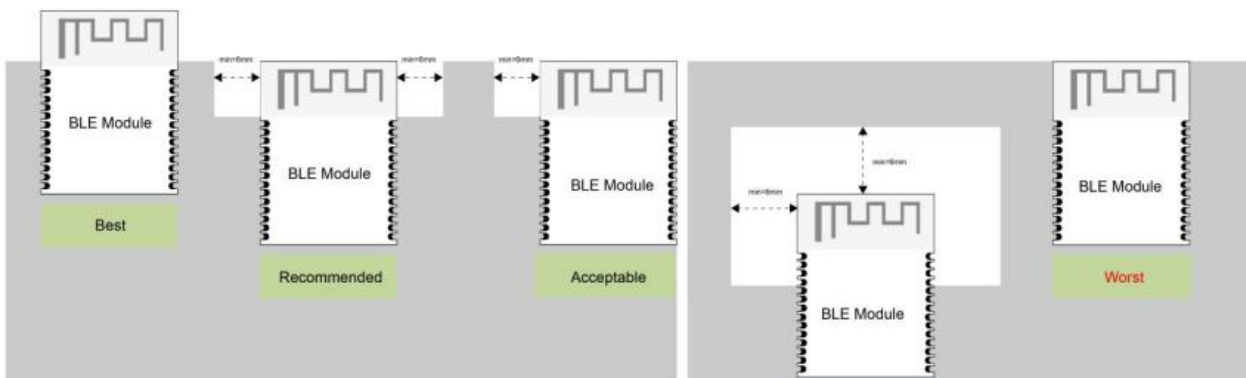
The antenna area of module shall lay clearance completely and should not be blocked by the metal. Otherwise it will have effect on antenna performance (As the picture indicated below).

(2) Placement of top-layer

The placement of top-layer in carrier board shall be lay copper completely to reduce the signal line in carrier board or other interference.

(3) Clearance

The upper and below area of antenna (including the case) shall have 4mm or more than 4mm clearance to reduce the influences for antenna.



*The Grey area above is Carrier board.

9.3 Installation and soldering

(1) Please do not lay copper under the module antenna. It can prevent the influence of signal radiation and the transmission distance from being affected.

9.4 Handling and storage

(1) Due to the fact that CMOS components are included in the module, it is better to eliminate static electricity at any methods when transporting or working with the module. Moreover, it is strongly recommended adding anti-ESD components to circuit design to hinder damage from real-life ESD events. Anti-ESD methods can be also used in mechanical design.



(2) Please store the modules within -40°C to $+125^{\circ}\text{C}$ before and after installation and make sure the modules is away from the direct sunlight exposure for a long duration. Modules should be far away from humid and salty air conditions, and any corrosive gasses or substances.

(3) Please not to wash the module. No-Clean Paste is used in production. The metal shield may be oxidized by the washing process and may lead to chemistry reaction with No-Clean Paste. If modules goes through the washing process, functions of the module may not guaranteed.

9.5 Life support applications

(1) The module is not design for life support device or system and not allowed to be used in destructive devices or system in any direct, or indirect ways. Minew is not responsible for compensation of any losses when applying modules under such application as described above.

(2) Minew shall not responsible for the customer's products or application.

10. Disclaimer

The factory has passed the ISO9001 quality management system, ISO14001 environmental management system and OHS18001 occupational health and safety assessment . Each product has been rigorously tested (transmission power test, sensitivity test, power consumption test, stability test, aging test, etc.).

* NOTICES:

- (1) The Bluetooth trade mark is owned by the Bluetooth SIG Inc. USA.
- (2) All other trademarks listed herein are owned by their respective owners.
- (3) All specifications are subject to change without notice.
- (4) Please do not use this specification for produce, sell or illegal purpose without Minew's authorization.
- (5) Minew have right to interpret all the items above.

11. Contact information

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